M1MA151AT1, M1MA152AT1

Preferred Device

Single Silicon Switching Diodes

These Silicon Epitaxial Planar Diodes are designed for use in ultra high speed switching applications. These devices are housed in the SC-59 package which is designed for low power surface mount applications.

Features

- Fast t_{rr} , < 3.0 ns
- Low C_D, < 2.0 pF
- Pb-Free Packages are Available

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Value	Unit	
Reverse Voltage	M1MA151AT1 M1MA152AT1	V _R	40 80	Vdc
Peak Reverse Voltage	M1MA151AT1 M1MA152AT1	V _{RM}	40 80	Vdc
Forward Current		I _F	100	mAdc
Peak Forward Current		I _{FM}	225	mAdc
Peak Forward Surge Cur	rent	I _{FSM} (Note 1)	500	mAdc

THERMAL CHARACTERISTICS

Rating	Symbol	Max	Unit
Power Dissipation	P_{D}	200	mW
Junction Temperature	T_J	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

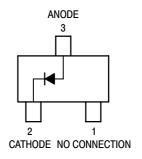
1. t = 1 SEC



ON Semiconductor®

http://onsemi.com

SC-59 PACKAGE SINGLE SILICON SWITCHING DIODES 40/80 V-100 mA SURFACE MOUNT





SC-59 CASE 318D

MARKING DIAGRAM



Mx = Device Code

x = A for 151B for 152

M = Date Code*

= Pb–Free Package

(Note: Microdot may be in either location)
*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

M1MA151AT1, M1MA152AT1

ELECTRICAL CHARACTERISTICS $(T_A = 25^{\circ}C)$

Characteristic		Symbol	Condition	Min	Max	Unit
Reverse Voltage Leakage Current	M1MA151AT1 M1MA152AT1	I _R	V _R = 35 V V _R = 75 V	-	0.1	μAdc
Forward Voltage		V _F	I _F = 100 mA	-	1.2	Vdc
Reverse Breakdown Voltage	M1MA151AT1 M1MA152AT1	V _R	I _R = 100 μA	40 80	-	Vdc
Diode Capacitance		C _D	V _R = 0, f = 1.0 MHz	-	2.0	pF
Reverse Recovery Time (Figure 1)		t _{rr} (Note 2)	$I_F = 10 \text{ mA}, V_R = 6.0 \text{ V},$ $R_L = 100 \Omega, I_{rr} = 0.1 I_R$	1	3.0	ns

^{2.} t_{rr} Test Circuit

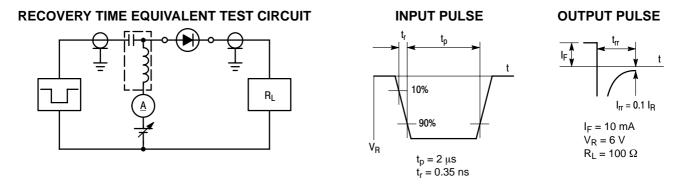


Figure 1. Reverse Recovery Time Equivalent Test Circuit

ORDERING INFORMATION

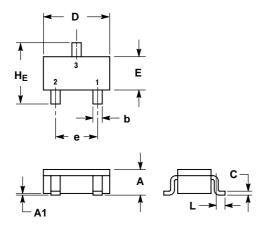
Device	Package	Shipping [†]	
M1MA151AT1	SC-59		
M1MA151AT1G	SC-59 (Pb-Free)	3000 /Tape & Reel	
M1MA152AT1	SC-59	3000 / Tape & Reel	
M1MA152AT1G	SC-59 (Pb-Free)		

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

M1MA151AT1, M1MA152AT1

PACKAGE DIMENSIONS

SC-59 CASE 318D-04 ISSUE G

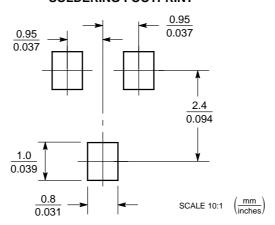


NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982
- 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS				INCHES	
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	1.00	1.15	1.30	0.039	0.045	0.051
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.35	0.43	0.50	0.014	0.017	0.020
С	0.09	0.14	0.18	0.003	0.005	0.007
D	2.70	2.90	3.10	0.106	0.114	0.122
Е	1.30	1.50	1.70	0.051	0.059	0.067
е	1.70	1.90	2.10	0.067	0.075	0.083
L	0.20	0.40	0.60	0.008	0.016	0.024
HE	2.50	2.80	3.00	0.099	0.110	0.118

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.